

LINEAR TECHNOLOGY MATERIALS DECLARATION

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(Engineering Calculation)

SSOP

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TOTAL MASS (g) : 0.079953

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|---------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.001460 | 1000000 | 18260.7109375 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000061 | 1000000 | 762.947509766 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.029933 | 975000 | 374382.09375 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000737 | 24000 | 9217.90722656 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000009 | 300 | 112.56603241 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000021 | 700 | 262.654052734 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.030700 | 1000000 | 383975.25 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.002272 | 1000000 | 28417.671875 | | |
| | | External Plating Total: | | | | 0.002272 | 1000000 | 28417.671875 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000246 | 1000000 | 3076.8046875 | | |
| Internal Plating Total: | | | | 0.000246 | 1000000 | 3076.8046875 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000558 | 750000 | 6979.09375 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000186 | 250000 | 2326.36474609 | | |
| Die Attach Total: | | | | 0.000744 | 1000000 | 9305.45898438 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.006605 | 150000 | 82610.9609375 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.036107 | 820000 | 451602.40625 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.001101 | 25000 | 13770.5771484 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000220 | 5000 | 2751.61401367 | | |
| | | Encapsulation Total: | | | | 0.044033 | 1000000 | 550735.5625 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000437 | 1000000 | 5465.70654297 | | |
| | | | | | TOTAL MASS (g) : | 0.079953 | | |